

TUSB3210 Universal Serial Bus General-Purpose Device Controller

Data Manual



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MSDS Bus Solutions

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Mailing Address:

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1 Introduction

The TUSB3210 has $8k \times 8$ RAM space for application development. A ROM based version of the TUSB3210 has $8k \times 8$ ROM space for predeveloped customer specific production applications. In addition, the programmability of the TUSB3210 makes it flexible enough to use for various other general USB I/O applications. Unique vendor identification and product identification (VID/PID) may be selected without the use of an external EEPROM. Using a 12 MHz crystal, the onboard oscillator generates the internal system clocks. The device may be programmed via an inter-IC (I²C) serial interface at power on from an EEPROM, or optionally, the application firmware may be downloaded from a host PC via USB. The popular 8052-based microprocessor allows several third party standard tools to be used for application development. In addition, the vast amounts of application code available in the general market may also be utilized (this may or may not require some code modification due to hardware variations).

1.1 Features

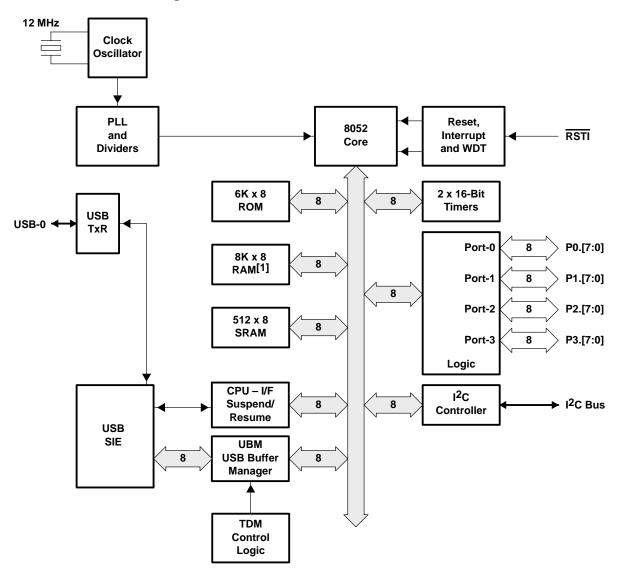
- Multiproduct support with one code and one chip (up to 16 products with one chip)
- Fully compliant with the USB release 1.1 specification
- Supports USB suspend/resume and remote wake-up operation
- Integrated 8052 Microcontroller with:
 - 256 × 8 RAM for internal data
 - $8k \times 8$ RAM code space available for downloadable firmware from host or I²C port. [1]
 - 512 × 8 shared RAM used for data buffers and endpoint descriptor blocks (EDB) [2]
 - Four 8052 GPIO ports, Port 0,1, 2 and 3
 - Master I²C controller for external slave device access
 - Watchdog timer
- Operates from a 12 MHz crystal
- On-chip PLL generates 48/12 MHz
- Supports a total of 4 input and 4 output endpoints
- Power-down mode
- Single 3.3 V operation [3]
- 64-pin TQFP package
- Applications include keyboard, bar code reader, flash memory reader, general-purpose controller

^[1] The TUSB3210 has 8K x 8 RAM for development.

 $[\]ensuremath{\left[2\right]}$ This is the buffer space for USB packet transactions.

^{[3] 1.8} V required only to support suspend mode.

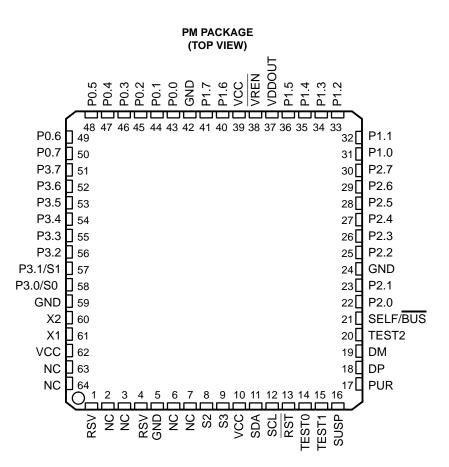
1.2 Functional Block Diagram



[1] The TUSB3210 has 8K x 8 RAM for development. 8k x 8 ROM version available. Contact TI Marketing

Figure 1–1. TUSB3210 Block Diagram

1.3 Terminal Assignments



1.4 Ordering Information

	PACKAGE			
TA	PLASTIC QUAD FLATPACK (PM)			
0°C to 70°C	TUSB3210PM			

1.5 Terminal Functions

TERM	INAL		
NAME NO.		1/0	DESCRIPTION
DM	19	I/O	Differential data minus USB
DP	18	I/O	Differential data plus USB
GND	5,24,42,5 9	I	Power supply ground
NC	2, 3, 6, 7, 63, 64		No connection
P0.0	43	I/O	General-purpose I/O port 0 bit 0, Schmitt-trigger input 100 μA active pullup, open drain output
P0.1	44	I/O	General-purpose I/O port 0 bit 1, Schmitt-trigger input 100 μA active pullup, open drain output
P0.2	45	I/O	General-purpose I/O port 0 bit 2, Schmitt-trigger input 100 µA active pullup, open drain output
P0.3	46	I/O	General-purpose I/O port 0 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output
P0.4	47	I/O	General-purpose I/O port 0 bit 4, Schmitt-trigger input 100 μA active pullup, open drain output
P0.5	48	I/O	General-purpose I/O port 0 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P0.6	49	I/O	General-purpose I/O port 0 bit 6, Schmitt-trigger input 100 µA active pullup, open drain output
P0.7	50	I/O	General-purpose I/O port 0 bit 7, Schmitt-trigger input 100 µA active pullup, open drain output
P1.0	31	I/O	General-purpose I/O port 1 bit 0, Schmitt-trigger input 100 µA active pullup, open drain output
P1.1	32	I/O	General-purpose I/O port 1 bit 1, Schmitt-trigger input 100 µA active pullup, open drain output
P1.2	33	I/O	General-purpose I/O port 1 bit 2, Schmitt-trigger input 100 µA active pullup, open drain output
P1.3	34	I/O	General-purpose I/O port 1 bit 3, Schmitt-trigger input 100 μA active pullup, open drain output
P1.4	35	I/O	General-purpose I/O port 1 bit 4, Schmitt-trigger input 100 µA active pullup, open drain output
P1.5	36	I/O	General-purpose I/O port 1 bit 5, Schmitt-trigger input 100 µA active pullup, open drain output
P1.6	40	I/O	General-purpose I/O port 1 bit 6, Schmitt-trigger input 100 µA active pullup, open drain output
P1.7	41	I/O	General-purpose I/O port 1 bit 7, Schmitt-trigger input 100 µA active pullup, open drain output
P2.0	22	I/O	General-purpose I/O port 2 bit 0, Schmitt-trigger input 100 µA active pullup, open drain output
P2.1	23	I/O	General-purpose I/O port 2 bit 1, Schmitt-trigger input 100 µA active pullup, open drain output
P2.2	25	I/O	General-purpose I/O port 2 bit 2, Schmitt-trigger input 100 µA active pullup, open drain output
P2.3	26	I/O	General-purpose I/O port 2 bit 3, Schmitt-trigger input 100 µA active pullup, open drain output
P2.4	27	I/O	General-purpose I/O port 2 bit 4, Schmitt-trigger input 100 µA active pullup, open drain output
P2.5	28	I/O	General-purpose I/O port 2 bit 5, Schmitt-trigger input 100 µA active pullup, open drain output
P2.6	29	I/O	General-purpose I/O port 2 bit 6, Schmitt-trigger input 100 µA active pullup, open drain output
P2.7	30	I/O	General-purpose I/O port 2 bit 7, Schmitt-trigger input 100 µA active pullup, open drain output
P3.0/S0	58	I/O	General-purpose I/O port 3 bit 0, Schmitt-trigger input 100 µA active pullup, open drain output
P3.1/S1	57	I/O	General-purpose I/O port 3 bit 1, Schmitt-trigger input 100 µA active pullup, open drain output
P3.2	56	I/O	General-purpose I/O port 3 bit 2
P3.3	55	I/O	General-purpose I/O port 3 bit 3, Schmitt-trigger input 100 μ A active pullup, open drain output; will not support INT1 input
P3.4	54	I/O	General-purpose I/O port 3 bit 4, Schmitt-trigger input 100 µA active pullup, open drain output
P3.5	53	I/O	General-purpose I/O port 3 bit 5, Schmitt-trigger input 100 μA active pullup, open drain output
P3.6	52	I/O	General-purpose I/O port 3 bit 6, Schmitt-trigger input 100 µA active pullup, open drain output
P3.7	51	I/O	General-purpose I/O port 3 bit 7, Schmitt-trigger input 100 µA active pullup, open drain output
PUR	17	0	Pullup resistor connection pin (3-state) push-pull CMOS output (±8 mA)
RST	13	Ι	Controller master reset signal, Schmitt-trigger input 100 µA active pullup
RSV	1, 4		Reserved (Do not connect these pins)
S2	8	Ι	VID/PID selection pin
S3	9	I	VID/PID selection pin

TERMINAL								
NAME	NO.	I/O	DESCRIPTION					
SCL	12	0	Serial clock I ² C; open drain output					
SDA	11	I/O	Serial data I ² C; open drain output					
SELF/BUS	21	Ι	USB power MODE select: self-powered (HIGH), bus-powered (LOW)					
SUSP	16	0	Suspend status signal: suspended (HIGH); unsuspended (LOW)					
TEST0	14	Ι	Test input0, Schmitt-trigger input 100 μA active pullup					
TEST1	15	Ι	Test input1, Schmitt-trigger input 100 μA active pullup					
TEST2	20	I	Test input2, Schmitt-trigger input 100 μA active pullup					
VCC	10,39,62	Ι	Power supply input 3.3 V typical					
VDDOUT	37	0	Power supply regulator output 1.8 V (May be used as an input when VREN is low)					
VREN	38	Ι	Voltage regulator enable: enable active LOW; disable active HIGH					
X1	61	Ι	12-MHz crystal input					
X2 60 O		0	12-MHz crystal output					

1.5 Terminal Functions (Continued)

2 Functional Description

2.1 MCU Memory Map

Figure 2–1 illustrates the MCU memory map under boot and normal operation. It must be noted that the internal 256 bytes of IDATA are not shown since it is assumed to be in the standard 8052 location (0000 to 00FF). The shaded areas represent the internal ROM/RAM.

When SDW bit = 0 (Boot mode): The 6k-ROM is mapped to address (0000-17FF) and is duplicated in location (8000-97FF) in code space. The internal 8k-RAM is mapped to address range (0000-1FFF) in data space. Buffers, MMR and I/O are mapped to address range (FD80-FFFF) in data space.

When SDW bit = 1 (Normal mode): The 6k-ROM is mapped to (8000-97FF) in code space. The internal 8k-RAM is mapped to address range (0000-1FFF) code space. Buffers, MMR and I/O are mapped to address range (FD80-FFFF) in data space.

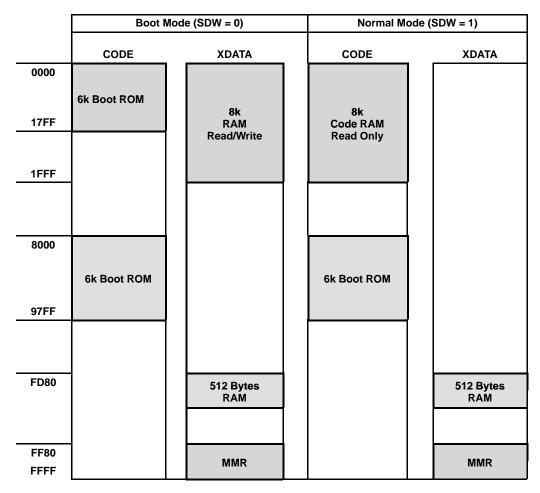


Figure 2–1. MCU Memory Map (TUSB3210)

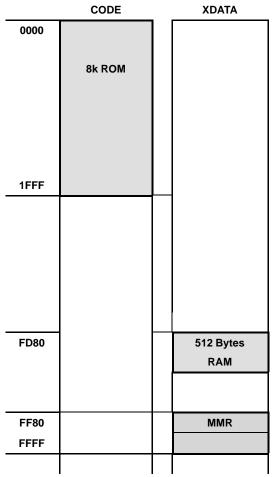


Figure 2–2. MCU Memory Map (ROM Version)

2.2 Miscellaneous Registers

2.2.1 TUSB3210 Boot Operation

Since the code-space is in RAM (with the exception of the boot ROM), the TUSB3210 firmware must be loaded from an external source. Two options for booting are available: an external serial EEPROM source connected to the I²C bus, or the host may be used via the USB. On device reset, the SDW bit (in ROM register) and CONT bit in USB Control Register (USBCTL) will be cleared. This will configure the memory space to boot mode (see memory map) and will keep the device *disconnected* from the host.

The first instruction will be fetched from location 0000 (which is in the 6k-ROM). The 8k-RAM will be mapped to XDATA space (location 0000h). MCU will execute a read from an external EEPROM and test to see if it contains the code (test for boot signature). If it contains the code, MCU will read from EEPROM and write to the 8k-RAM in XDATA space. If not, MCU will proceed to boot from USB.

Once the code is loaded, the MCU will set SDW to 1. This will switch the memory map to normal mode, i.e. the 8k-RAM will be mapped to code space, and the MCU will start executing from location 0000h. Once the switch is done, the MCU will set CONT to 1 (in USBCTL register) This will *connect* the device to the USB bus, resulting in the normal USB device enumeration.

2.2.2 MCNFG: MCU Configuration Register

This register is used to control the MCU clock rate.

7	6	5	4	3	2	1	0	
12/48	XINT	RSV	R3	R2	R1	R0	SDW	
R/W	R/W	R/O	R/O	R/O	R/O	R/O	R/W	-

BIT	NAME	RESET		FUNCTION				
0	SDW	0	This bit ena	This bit enables/disables boot ROM. In the ROM version of the controller, this bit has no effect.				
			SDW = 0	When clear, MCU executes from the 6k boot ROM space. The boot ROM appears in two locations: 0000 and 8000h. The 8k RAM is mapped to XDATA space; therefore, Read/Write operation is possible. This bit is set by MCU after the RAM load is completed. MCU cannot clear this bit. It is cleared on power-up-reset or function reset.				
			SDW = 1	When set by MCU, the 6k boot ROM maps to location 8000h, and the 8k RAM is mapped to code-space, starting at location 0000h. At this point, MCU executes from RAM, and write operation is disabled (No write operation is possible in code space).				
4–1	R[3:0]	No affect	These bits	reflect the device revision number				
5	RSV	0	Reserved					
6	XINT	0	XINT = 0 II	INT1 source control bit. XINT = 0 INT1 is connected to P3.3-pin and operates as a standard INT1 interrupt XINT = 1 INT1 is connected to the OR of Port–2 inputs.				
7	12/48	0	12/48 = 0	Fhis bit selects 12 or 48MHz clock for MCU 12/48 = 0 12 MHz 12/48 = 1 48 MHz				

2.2.3 PUR_n: GPIO Pullup Register for Port n (n = 0 to 3)

_	7	6	5	4	3	2	1	0	_
	Pin7	Pin6	Pin5	Pin4	Pin3	Pin2	Pin1	Pin0	
	R/W								
1				1					-

BIT	NAME	RESET	FUNCTION
0–7	PinN (N = 0 to 7)	0	The MCU may write to this register. If the MCU sets this bit to 1, the pullup resistor is disconnected from the pin. If the MCU clears this bit to 0, the pullup resistor is connected to the pin. The pullup resistor is connected to V_{CC} power supply.

2.2.4 INTCFG: Interrupt Configuration

7	6	5	4	3	2	1	0
RSV	RSV	RSV	RSV	13	12	11	10
R/O	R/O	R/O	R/O	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
0–3	I[3:0]	0010	The MCU may write to this register to set the interrupt delay time for Port 2 on the MCU. The value of the lower nibble represents the delay in ms. Default after reset is 2 ms.
4–7	RSV	0	Reserved

2.2.5 WDCSR: Watchdog Timer, Control, and Status Register

A watchdog timer (WDT) with 1ms clock is provided. If this register is not accessed for a period of 32ms, the WDT counter will reset the MCU. (See Figure 2–3, Reset Diagram). When the IDL bit in PCON is set, the WDT will be suspended until an interrupt is detected. At this point, the IDL bit will be cleared and the WDT will resume operation.

7	6	5	4	3	2	1	0	
WDE	WDR	RSV	RSV	RSV	RSV	RSV	WDT]
R/W	R/W	R/O	R/O	R/O	R/O	R/O	W/O	-
BIT	NAME	RESET					FUNCTIC)N
0	WDT	0	period of 37	MCU must write a 1 to this bit to prevent the WDT from resetting the MCU. If MCU does not write a 1 in a period of 31ms, the WDT will reset the device. Writing a 0 has no effect on the WDT. (WDT is a 5-bit counter using 1ms CLK). This bit is read as 0.				
5–1	RSV	0	Reserved = 0					
6	WDR	0	U U	Watchdog reset indication bit. This bit indicates if the reset occurred due to power-on reset or watchdog timer reset.				
			WDR = 0 A power-up or USB reset occurred.					
			WDR = 1	A watcho effect.	log timeout	resetoccurr	ed. To clear	this bit, the MCU must write a 1. Writing a 0 has no
7	WDE	0	Watchdog Timer Enable.					
			WDE = 0	NDE = 0 This bit is cleared only on power-up, USB-reset (if enabled) or WDT reset.				
			WDE = 1		or USB res			start running. MCU cannot disable the WDT. Only rit. When MCU is in idle state (IDL = 1), the WDT is

2.2.6 PCON: Power Control Register (at SFR 87h)

7	6	5	4	3	2	1	0
SMOD	RSV	RSV	RSV	GF1	GF0	RSV	IDL
R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/W

BIT	NAME	RESET		FUNCTION		
0	IDL	0	MCU idle mode bit. This bit can be set by MCU and is cleared only by INT1 interrupt.			
			$IDL = 0 \qquad MCU is NOT in idle mode. This bit is cleared by INT1 interrupt logic when INT1 is as at least 400 \mu s.$			
			w g	MCU is in idle mode and RAM is in low-power mode. The oscillator/APLL is off and the WDT vill be suspended. When in suspend mode, only INT1 can be used to exit from idle mode and generate an interrupt. INT1 must be asserted for at least 400µs for the interrupt to be ecognized.		
1	RSV	0	Reserved			
3–2	GF[1:0]	00	General-purpose bits. MCU can write and read them.			
6–4	RSV	0	Reserved			
7	SMOD	0	Double baud ra	ate control bit. For more information see UART serial interface in M8052 core specification.		

2.3 Buffers + I/O RAM Map

The address range from FD80 to FFFF is reserved for data buffers, setup packet, endpoint descriptor blocks (EDB), and all I/O. RAM space of 512 bytes [FD80–FF7F] is used for EDB and buffers. The FF80–FFFF range is used for memory mapped registers (MMR). Table 2–1 represents the internal XDATA space allocation.

DESCRIPTION	ADDRESS RANGE	
	FFFF	
Internal MMR (Memory mapped registers)	Ŷ	
	FF80	
	FF7F	
EDB (Endpoint descriptor blocks)	Ŷ	
	FF08	
	FF07	
Setup packet buffer	\uparrow	
	FF00	
	FEFF	512 byte
Input endpoint-0 buffer	↑ 	RAM
	FEF8	
	FEF7 ↑	
Output endpoint-0 buffer	FEF0	
	FEEF	
Data buffers (367 bytes)	Ŷ	
	FD80	

Table 2–1. XDATA Space

ADDRESS	REGISTER	DESCRIPTION
FFFF	FUNADR	FUNADR: Function address register
FFFE	USBSTA	USBSTA: USB status register
FFFD	USBMSK	USBMSK: USB interrupt mask register
FFFC	USBCTL	USBCTL: USB control register
\uparrow	RESERVED	
FFF6	VIDSTA	VIDSTA: VID/PID status register
\uparrow	RESERVED	
FFF3	I2CADR	I2CADR: I2C address register
FFF2	I2CDAI	I2CDAI: I2C data-input register
FFF1	I2CDAO	I2CDAO: I2C data-output register
FFF0	I2CSTA	I2CSTA: I2C status and control register
↑	RESERVED	
FF97	PUR3	Port 3 pullup resistor register
FF96	PUR2	Port 2 pullup resistor register
FF95	PUR1	Port 1 pullup resistor register
FF94	PUR0	Port 0 pullup resistor register
FF93	WDCSR	WDCSR: Watchdog timer, control & status register
FF92	VECINT	VECINT: Vector interrupt register

ADDRESS	REGISTER	DESCRIPTION
FF91	RESERVED	
FF90	MCNFG	MCNFG: MCU configuration register
\uparrow	RESERVED	
FF84	INTCFG	INTCFG: Interrupt delay configuration register
FF83	OEPBCNT_0	OEPBCNT_0: Output endpoint-0 byte count register
FF82	OEPCNFG_0	OEPCNFG_0: Output endpoint-0 configuration register
FF81	IEPBCNT_0	IEPBCNT_0: Input endpoint-0 byte count register
FF80	IEPCNFG_0	IEPCNFG_0: Input endpoint-0 configuration register

Table 2–2. Memory Mapped Registers Summary (XDATA Range = FF80 \rightarrow FFF) (Continued)

Table 2–3. EDB and Buffer Allocations in XDATA

ADDRESS		DESCRIPTION
FF7F ↑	(32-bytes)	RESERVED
FF60		
FF5F		
\uparrow	(8–bytes)	Input endpoint_3: configuration
FF58		
FF57		
↑ 	(8–bytes)	Input endpoint_2: configuration
FF50		
FF4F ↑	(0, b, t, z)	
FF48	(8-bytes)	Input endpoint_1: configuration
FF47		
114/		
↑	(40-bytes)	RESERVED
FF20		
FF1F		
\uparrow	(8–bytes)	Output endpoint_3: configuration
FF18		
FF17		
\uparrow	(8–bytes)	Output endpoint_2: configuration
FF10		
FF0F		
1	(8–bytes)	Output endpoint_1: configuration
FF08		
FF07 ↑		
FF00	(8-bytes)	Setup packet block
FEFF		
r⊑rr ↑	(8-bytes)	Input endpoint_0 buffer
FEF8	(o-bytes)	
ILIU		

ADDRESS		DESCRIPTION
FEF7		
\uparrow	(8–bytes)	Output endpoint_0 buffer
FEF0		
FEEF	TOPBUFF	Top of buffer space
\uparrow		
1		Buffers space
FD80	STABUFF	Start of buffer space

Table 2–3. EDB and Buffer Allocations in XDATA (Continued)

2.4 Endpoint Descriptor Block (EDB-1 to EDB-3)

Data transfers between USB, MCU and external devices are defined by an endpoint descriptor block (EDB). Four input and four output EDBs are provided. With the exception of EDB–0 (I/O Endpoint–0), all EDBs are located in SRAM as shown in Table 2–3. Each EDB contains information describing the X and Y buffers. In addition, it provides general status information.

Table 2–4 illustrates the EDB entries for EDB–1 to EDB–3. EDB–0 registers will be described separately.

Offset	ENTRY NAME	DESCRIPTION
07	EPSIZXY_n	I/O endpoint_n: X/Y buffer size
06	EPBCTY_n	I/O endpoint_n: Y byte count
05	EPBBAY_n	I/O endpoint_n: Y buffer base address
04	SPARE	Not used
03	SPARE	Not used
02	EPBCTX_n	I/O endpoint_n: X byte count
01	EPBBAX_n	I/O endpoint_n: X buffer base address
00	EPCNF_n	I/O endpoint_n: configuration

2.4.1 **OEPCNF_n:** Output Endpoint Configuration (n=1 to 3)

7	6	5	4	3	2	1	0					
UBME	ISO	TOGLE	DBUF	STALL	USBIE	RSV	RSV					
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/O	-				
BIT	NAME	RESET					FUNCTION	J				
1–0	RSV	0	Reserved									
2	USBIE	x	USBIE = 0	B interrupt enable on transaction completion. Set/clear by MCU. BIE = 0 no interrupt BIE = 1 interrupt on transaction completion								
3	STALL	0	USB stall co	B stall condition indication. Set/clear by MCU.								
			STALL = 0	TALL = 0 No stall								
			STALL = 1	USB stall c	ondition. If s	et by MCU,	a STALL hai	ndshake is initiated and the bit is cleared by MCU.				
4	DBUF	х	Double buffe	er enable. S	et/clear by N	ICU.						
			DBUF = 0	Primary bu	ffer only (X-	-buffer only)					
			DBUF = 1	Toggle bit s	selects buffe	er						
5	TOGLE	х	USB Toggle	bit. This bit	reflects the	toggle seq	uence bit of	DATA0, DATA1				
6	ISO	x	ISO = 0	SO = 0 Non-isochronous transfer. This bit must be cleared by MCU since only Non-isochronous transfer is supported.								
7	UBME	х	UBME = 0 U	JBM enable/disable bit. Set/clear by MCU. JBME = 0 UBM cannot use this endpoint. JBME = 1 UBM can use this endpoint.								

2.4.2	OEPBBAX	_n: Output	Endpoint X-Buffer	Base-Address	(n=1 to	3)
-------	---------	------------	--------------------------	--------------	---------	----

7	6	5	4	3	2	1	0					
A ₁₀	Ag	A ₈	A7	A ₆	A5	A ₄	A ₃					
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W					
BIT	NAME	RESET		FUNCTION								
7–0	A[10:3]	x	MCU. UBN	A[10:3] of X–buffer base address (padded with 3-LSB of zeros for a total of 11-bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.								

2.4.3 **OEPBCTX_n:** Output Endpoint X Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0
NAK	С ₆	C ₅	C4	С ₃	C ₂	С ₁	C ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6–0	C[6:0]	x	X-Buffer Byte count: $X000.0000b > Count = 0$ $X000.0001b > Count = 1 byte$::::X011.1111b > Count = 63 bytesX100.0000b > Count = 64 bytesAny value $\geq 100.0001b$ produces unpredictable results.
7	NAK	х	NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from Host (host-out request is NAK)

2.4.4 **OEPBBAY_n:** Output Endpoint Y-Buffer Base-Address (n=1 to 3)

DIT		DECET					FUNCTION	
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
A ₁₀	Ag	A ₈	A7	A ₆	A5	A ₄	A ₃	
7	6	5	4	3	2	1	0	

BIT	NAME	RESET	FUNCTION
7–0	A[10:3]		A[10:3] of Y–buffer base address (padded with 3-LSB of zeros for a total of 11 bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.5 **OEPBCTY_n: Output Endpoint Y Byte Count (n=1 to 3)**

7	6	5	4	3	2	1	0
NAK	С ₆	C ₅	C4	C ₃	C ₂	С ₁	С ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6–0	C[6:0]	x	Y-Byte count: $X000.0000b > Count = 0$ $X000.0001b > Count = 1 byte$::::X011.1111b > Count = 63 bytesX100.0000b > Count = 64 bytesAny value \geq 100.0001b will result in unpredictable results.
7	NAK	х	NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from host (host-out request is NAK)

2.4.6 **OEPSIZXY_n:** Output Endpoint X/Y Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0			
RSV	S ₆	S ₅	S ₄	S ₃	S ₂	S ₁	s ₀			
R/O	R/W	R/W	R/W	R/W	R/W	R/W	R/W			
BIT	NAME	RESET		FUNCTION						
6–0	S[6:0]	x	0000.0000 0000.000 : : 0011.1111 0100.0000	$(AND Y-Buffer size:)0000.0000b > Count = 0)0000.0001b > Count = 1 byte)011.1111b > Count = 63 bytes)100.0000b > Count = 64 bytes Any value \geq 100.0001b produces unpredictable results.$						
7	RSV	0	Reserved	Reserved						

2.4.7 IEPCNF_n: Input Endpoint Configuration (n=1 to 3)

7	6	5	4	3	2	1	0
UBME	ISO	TOGLE	DBUF	STALL	USBIE	RSV	RSV
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION						
1–0	RSV	х	Reserved =	0						
2	USBIE	х	USBIE = 0	B interrupt enable on transaction completion. BIE = 0 No interrupt BIE = 1 Interrupt on transaction completion						
3	STALL	0	USB stall co	SB stall condition indication. Set by UBM, but can be set/cleared by MCU.						
			STALL = 0	ALL = 0 No stall						
			STALL = 1	automatically.						
4	DBUF	х	Double buff	er enable						
			DBUF = 0	Primary buffer only (X-buffer only)						
			DBUF = 1	Toggle bit selects buffer						
5	TOGLE	х	USB Toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1						
6	ISO	х	ISO = 0	Non-isochronous transfer. This bit must be cleared by MCU since only Non-isochronous transfer is supported.						
7	UBME	х	UBME = 0 L	e/disable bit. Set/clear by MCU. JBM cannot use this endpoint. JBM can use this endpoint.						

2.4.8 IEPBBAX_n: Input Endpoint X-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0
A ₁₀	Ag	A ₈	A7	A ₆	A5	A ₄	A ₃
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
7–0	A[10:3]	х	A[10:3] of X-buffer base address (padded with 3-LSB of zeros for a total of 11 bits). This value is set by the MCU. UBM or DMA uses this value as the start-address of a given transaction. Furthermore, UBM or DMA does not change this value at the end of a transaction.

2.4.9 IEPBCTX_n: Input Endpoint X-Byte Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0	
NAK	С ₆	C5	C4	C ₃	C ₂	C ₁	C ₀	
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
BIT	NAME	RESET					FUNCTIO	N
6–0	C[6:0]	x	X000.000 X000.000 : : X011.1111 X100.000	Byte count 0b > Count 1b > Count b > Count = 0b > Count ≥ 100.0001	= 0 = 1 byte = 63 bytes	s unpredicta	ble results.	
7	NAK	x			ains a valid npty (host-ir		iost-in trans NAK)	action

2.4.10 IEPBBAY_n: Input Endpoint Y-Buffer Base-Address (n=1 to 3)

7	6	5	4	3	2	1	0	
A ₁₀	Ag	A ₈	A7	A ₆	A5	A ₄	A ₃	
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
BIT	NAME	RESET					FUNCTIO	N
7–0	A[10:3]	х	A[10:3] of	Y-buffer bas	se address (haddad wit	3-ISB of 7	eros for a total of 11 bits). This value is set by the

2.4.11 IEPBCTY_n: Input Endpoint Y Byte Count (n=1 to 3)

7	6	5	4	3	2	1	0
NAK	C ₆	C ₅	C4	С ₃	C ₂	с ₁	C ₀
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

BIT	NAME	RESET	FUNCTION
6–0	C[6:0]	x	X-Byte count: $X000.000b > Count = 0$ $X000.0001b > Count = 1 byte$:::X011.1111b > Count = 63 bytesX100.0000b > Count = 64 bytesAny value \geq 100.0001b produces unpredictable results.
7	NAK	x	NAK = 0 Buffer contains a valid packet for host-in transaction NAK = 1 Buffer is empty (host-in request is NAK)

7	6	5	4	3	2	1	0	
RSV	S ₆	S ₅	S ₄	S ₃	S ₂	S ₁	S ₀	
R/O	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
BIT	NAME	RESET					FUNCTIO	N Contraction of the second se
6–0	S[6:0]	x	0000.0000 0000.000 : : 0011.1111 0100.0000	Buffer size b > Count = b > Count = b > Count = b > Count = b > Count =	= 0 = 1 byte = 63 bytes = 64 bytes	unpredictal	ole results.	
7	RSV	х	Reserved					

2.4.12 IEPSIZXY_n: Input Endpoint X/Y-Buffer Size (n=1 to 3)

2.5 Endpoint-0 Descriptor Registers

Unlike EDB-1 to EDB-3, which are defined as memory entries in SRAM, Endpoint-0 is described by a set of 4 registers (two for output and two for input). Table 2–5 defines the registers and their respective addresses used for EDB-0 description. EDB-0 has no *Base-Address-Register*, since these addresses are hardwired to FEF8 and FEF0. Note that the bit positions have been preserved to provide consistency with EDB-n (n = 1 to 3).

	14610		
ADDRESS	REGISTER NAME	DESCRIPTION	BASE ADDRESS
FF83	OEPBCNT_0	Output endpoint_0: byte count register	
FF82	OEPCNFG_0	Output endpoint_0: configuration register	FEF0
FF81	IEPBCNT_0	Input endpoint_0: byte count register	
FF80	IEPCNFG_0	Input endpoint_0: configuration register	FEF8

Table 2–5.	Input/Output EDB-0 Registers

2.5.1 IEPCNFG_0: Input Endpoint-0 Configuration Register

7	6	5	4	3	2	1	0
UBME	RSV	TOGLE	RSV	STALL	USBIE	RSV	RSV
R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION
1–0	RSV	0	Reserved	
2	USBIE	0	USBIE = 0	pt enable on transaction completion. Set/clear by MCU No interrupt nterrupt on transaction completion
3	STALL	0	USB stall co	ndition indication. Set/clear by MCU.
			STALL = 0	No stall
			STALL = 1	USB stall condition. If set by MCU, a STALL handshake is initiated and the bit is cleared automaticallly by next setup transaction.
4	RSV	0	Reserved	
5	TOGLE	0	USB toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1
6	RSV	0	Reserved	
7	UBME	0	UBME = 0 L	e/disable bit. Set/clear by MCU. JBM cannot use this endpoint. JBM can use this endpoint.

2.5.2 IEPBCNT_0: Input Endpoint-0 Byte Count Register

7	6	5	4	3	2	1	0		
NAK	RSV	RSV	RSV	C3	C ₂	С ₁	С ₀		
R/W	R/O	R/O	R/O	R/W	R/W	R/W	R/W		
BIT	NAME	RESET		FUNCTION					
3–0	C[3:0]	0000	Byte cour 0000b > 0 : : 0111b > 0 1000b > 0 1001b to 1	Count = 0 Count =7 Count = 8	eserved. (If	used, defau	ilts to 8)		
6–4	RSV	0	Reserved						
7	NAK	1				backet for he request is f	ost-in transa NAK)		

2.5.3 **OEPCNFG_0:** Output Endpoint-0 Configuration Register

7	6	5	4	3	2	1	0
UBME	RSV	TOGLE	RSV	STALL	USBIE	RSV	RSV
R/W	R/O	R/O	R/O	R/W	R/W	R/O	R/O

BIT	NAME	RESET		FUNCTION			
1–0	RSV	0	Reserved	Reserved			
2	USBIE	0	USBIE = 0	USB interrupt enable on transaction completion. Set/clear by MCU USBIE = 0 no interrupt USBIE = 1 interrupt on transaction completion			
3	STALL	0	USB stall co	ondition indication. Set/clear by MCU.			
			STALL = 0	No stall			
			STALL = 1 USB stall condition. If set by MCU, a STALL handshake is initiated and the bit is clear automatically.				
4	RSV	0	Reserved				
5	TOGLE	0	USB toggle	bit. This bit reflects the toggle sequence bit of DATA0, DATA1			
6	RSV	0	Reserved				
7	UBME	0	UBME = 0 l	e/disable bit. Set/clear by MCU. JBM cannot use this endpoint. JBM can use this endpoint.			

2.5.4 OEPBCNT_0: Output Endpoint-0 Byte Count Register

7	6	5	4	3	2	1	0			
NAK	RSV	RSV	RSV	C ₃	C2	С ₁	С ₀			
R/W	R/O	R/O	R/O	R/W	R/W	R/W	R/W			
BIT	NAME	RESET	I	FUNCTION						
3–0	C[3:0]	0000	0000b > C : : 0111b > C 1000b > C	Byte count: 0000b > Count = 0 : 0111b > Count =7 1000b > Count = 8 1001b to 1111b are reserved. (If used, defaults to 8)						
6–4	RSV	0	Reserved	Reserved = 0						
7	NAK	1		NAK= 0 No valid data in buffer. Ready for host out NAK= 1 Buffer contains a valid packet from host. (NAK the host)						

2.6 USB Registers

2.6.1 FUNADR: Function Address Register

This register contains the device function address.

7	6	5	4	3	2	1	0
RSV	FA6	FA5	FA4	FA3	FA2	FA1	FA0
R/O	R/W						

BIT	NAME	RESET	FUNCTION
6–0	FA[6:0]	0000000	These bits define the current device address assigned to the function. MCU writes a value to this register as a result of <i>SET-ADDRESS</i> host command.
7	RSV	0	Reserved

2.6.2 USBSTA: USB Status Register

All bits in this register are set by the hardware and will be cleared by MCU when writing a 1 to the proper bit location (writing a 0 has no effect). In addition, each bit can generate an interrupt if its corresponding mask bit is set (R/C notation indicates read and clear only by MCU).

7	6	5	4	3	2	1	0		
RSTR	SUSR	RESR	PWOFF	PWON	SETUP	RSV	STPOW		
R/C	R/C	R/C	R/C	R/C	R/C	R/O	R/C		
BIT	NAME	RESET		FUNCTION					
0	STPOW	0		SETUP overwrite bit. Set by hardware when setup packet is received while there is already a packet in the setup buffer.					
			STPOW =	STPOW = 0 MCU can clear this bit by writing a 1. (Writing 0 has no effect)					
			STPOW =	1 SETU	P overwrite				
1	RSV	0	Reserved						
2	SETUP	0			eceived bit. 1, IN and O	UT on end	point-0 is NA	K regardless of the value of their real NAK bits.	
			SETUP = () MCU	can clear th	is bit by wri	ting a 1. (Wri	iting 0 has no effect)	
			SETUP = ²	I SETU	P transactio	n received			
3	PWON	0	Power on I This bit ind			rt-3 has bee	en received.	This bit generates a PWON interrupt (If enabled).	
			PWON = 0	MCU	can clear thi	is bit by wri	ting a 1. (Wri	iting 0 has no effect)	
			PWON = 1	Powe	r on to Port-	3 has been	received.		
4	PWOFF	0			Port-3. This interrupt (If		es whether	power-off to Port-3 has been received. This bit	
			PWOFF =	0 MCU	can clear th	is bit by wri	ting a 1. (Wri	iting 0 has no effect)	
			PWOFF =	1 Powe	r off to Port-	3 has been	received		
5	RESR	0	Function re	esume requ	uest bit				
			RESR = 0	MCU	can clear thi	is bit by wri	ting a 1. (Wri	iting 0 has no effect)	
			RESR = 1	Funct	ion resume i	s detected			
6	SUSR	0	Function suspended request bit. This bit is set in response to a global or selective suspend condition. SUSR =0 MCU can clear this bit by writing a 1. (Writing 0 has no effect) SUSR =1 Function suspend is detected.						
7	RSTR	0	USB functi RSTR = 0	Function reset request bit. This bit is set in response to host initiating a port reset. This bit is not affected by USB function reset. RSTR = 0 MCU can clear this bit by writing a 1. (Writing 0 has no effect) RSTR = 1 Function reset is detected.					

7	6	5	4	3	2	1	0			
RSTR	SUSR	RESR	PWOFF	PWON	SETUP	RSV	STPOW			
R/W	R/W	R/W	R/W	R/W	R/W	R/O	R/W			
BIT	NAME	RESET					FUNCTION			
0	STPOW	0	STPOW =	0 STPOV	errupt enable V interrupt d V interrupt e	isabled				
1	RSV	0	Reserved	= 0						
2	SETUP	0	SETUP =	SETUP interrupt enable bit SETUP = 0 SETUP interrupt disabled SETUP = 1 SETUP interrupt enabled						
3	PWON	0	PWON = 0	Power-on interrupt enable bit PWON = 0 PWON interrupt disabled PWON = 1 PWON interrupt enabled						
4	PWOFF	0	Power-off interrupt enable bit PWOFF = 0 PWOFF interrupt disabled PWON = 1 PWOFF interrupt enabled							
5	RESR	0	Function resume interrupt enable RESR = 0 function resume interrupt disabled RESR = 1 function resume interrupt enabled							
6	SUSR	0	Function suspend interrupt enable SUSR = 0 function suspend interrupt disabled SUSR = 1 function suspend interrupt enabled							
7	RSTR	0	Function reset interrupt enable RSTR = 0 function reset interrupt disabled RSTR = 1 function reset interrupt enabled							

2.6.3 USBMSK: USB Interrupt Mask Register

2.6.4 USBCTL: USB Control Register

Unlike the other registers, this register is cleared by the power-up-reset signal only. The USB-reset cannot reset this register. (See Figure 2–3: Reset Diagram)

7	6	5	4	3	2	1	0			
CONT	RSV	RWUP	FRSTE	RWE	B/S	SIR	DIR			
R/W	R/O	R/W	R/W	R/W	R/W	R/W	R/W			
BIT	NAME	RESET					FUNCTIO	N		
0	DIR	0	transfer dir DIR = 0 > 0	As a response to a setup packet, the MCU will decode the request and set or clear this bit to reflect the data ransfer direction. DIR = 0 > USB data OUT transaction. (From host to TUSB3210) DIR = 1 > USB data IN transaction. (From TUSB3210 to host)						
1	SIR	0	SETUP int interrupt is			bit is contro	olled by the	MCU to indicate to the hardware when SETUP		
			SIR = 0	SETUP i routine.	interrupt is	not served.	MCU will c	lear this bit before exiting the SETUP interrupt		
			SIR = 1	SETUP i	nterrupt is i	n progress.	MCU will se	et this bit when servicing the SETUP interrupt.		
2	B/S	0	B/S = 0 > 1	Bus/Self power control bit B/S = 0 > The device is bus-powered B/S = 1 > The device is self-powered						
3	RWE	0	Remote wa	ake-up ena	ble bit.					
			RWE = 0	MCU cle	ars it when	host sends	command to	o clear the feature.		
			RWE = 1	MCU wri feature	tes 1 to it w	hen host se	nds set dev	ice feature command to enable remote wake-up		
4	FRSTE	1	FRSTE = 0) function re		connected to	o MCU rese	ects the USB function reset from the MCU reset. t		
5	RWUP	0	Device rem	note wake-	up request.	This bit is s	et by MCU a	and is cleared automatically.		
			RWUP = 0	Writing a	0 to this bit	has no effe	ect.			
			RWUP = 1	RWUP = 1 When MCU writes a 1, a Remote wake-up pulse is generated.						
6	RSV	0	Reserved							
7	CONT	0	Connect/Disconnect Bit CONT = 0 Upstream port is disconnected. Pullup disabled CONT = 1 Upstream port is connected. Pullup enabled							

2.6.5 VIDSTA: VID/PID Status Register

This register is used to read the value on four external pins. The firmware can use this value to select one of the vendor identification/product identifications (VID/PID) stored in memory. The TUSB3210/D supports up to 16 unique VID/PIDs with application code to support different products. This provides a unique opportunity for original equipment manufacturers (OEM) to have one device ROM programmed to support up to 16 different product lines by using S0–S3 to select VID/PID and behavioral application code for the selected product.

7	6	5	4	3	2	1	0	
RSV	RSV	RSV	RSV	S3	S2	S1	S0]
R/O	-							

BIT	NAME	RESET	FUNCTION
3–0	S[3:0]	х	VID/PID selection bits. These bits reflect the status of the external pins as defined by Table 2–7. Note that a pin tied Low will be reflected as 0 and a pin tied high will be reflected as a 1.
7–4	RSV	0	Reserved = 0

	PIN	VIDSTA REGISTER				
NO.	NAME	S[3:0]	COMMENTS			
58	P3.0	S0	Dual function P3.0 I/O or S0 input			
57	57 P3.1 S1		Dual function P3.1 I/O or S1 input			
8	S2	S2	S2-pin is input			
9	S3	S3	S3-pin is input			

Table 2–6. External Pins Mapping to S[3:0] in VIDSTA Register

2.7 Function Reset and Power-Up Reset Interconnect

Figure 2–3 represents the logical connection of USB-function-reset ($\overline{\text{USBR}}$) and power-up-reset ($\overline{\text{RST}}$ -pin). The internal RESET signal is generated from the RST pin (PURS signal) or from the USB-reset ($\overline{\text{USBR}}$ signal). The USBR can be enabled or disabled by the FRSTE bit in the USBCTL register (on power up FRSTE is = 0). The internal RESET is used to reset all registers and logic, with the exception of the USBCTL and MISCTL registers. The USBCTL and MCU configuration register (MCNFG) are cleared by PURS signal only.

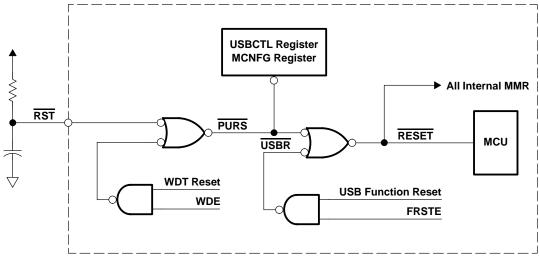


Figure 2–3. Reset Diagram

2.8 Pullup Resistor Connect/Disconnect

After reading firmware into RAM the TUSB3210 can re-enumerate using the new firmware (no need to physically disconnect and re-connect the cable). Figure 2–4 shows an equivalent circuit implementation for *Connect* and *Disconnect* from a USB up-stream port (also see Firgure 4–4b). When CONT bit in USBCTL register is 1, the CMOS driver sources VDD to the pullup resistor (PUR pin) presenting a normal connect condition to the USB hub (high speed). When CONT bit is 0, PUR pin is driven low. In this state, the 1.5 k Ω resistor is connected to GND, resulting in device *disconnection* state. The PUR driver is a CMOS driver that can provide (VDD–0.1) volt minimum at 8 mA source current.

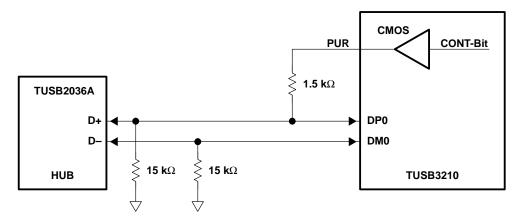


Figure 2–4. Pullup Resistor Connect/Disconnect Circuit

2.9 8052 Interrupt and Status Registers

All 8052 standard 5 interrupt sources are preserved. SIE is the standard interrupt enable register, which controls the five interrupt sources. All the additional interrupt sources are connected together as an OR to generate EX0. XINTO# signal is provided to interrupt an external MCU (see Interrupt connection diagram, Figure 2–5).

INTERRUPT SOURCE	DESCRIPTION	START ADDRESS	COMMENTS						
ES	UART interrupt	0023H							
ET1	Timer-1 interrupt	001BH							
EX1	Internal INT1	0013H	Used for P2[7:0] interrupt						
ET0	Timer–0 interrupt	000BH							
EX0	Internal INT0	0003H	Used for all internal peripherals						
Reset		0000H							

Table 2–7. 8052 Interrupt Location Map

7	6	5	4	3	2	1	0	
EA	RSV	RSV	ES	ET1	EX1	ET0	EX0	
R/W	R/O	R/O	R/W	R/W	R/W	R/W	R/W	_
BIT	NAME	RESET					FUNCTIO	DN
0	EX0	0	EX0 = 0 ex	xternal inter	ernal interru rrupt-0 is dis rrupt-0 is en	abled		
1	ET0	0	ET0 = 0 tir	mer-0 interr	er-0 interrup upt is disab upt is enabl	led		
2	EX1	0	EX1 = 0 e	xternal inter	ernal interru rrupt-1 is dis rrupt-1 is en	sabled		
3	ET1	0	ET1 = 0 tir	mer-1 interr	er-1 interrup upt is disab upt is enabl	led		
4	ES	0	ES = 0 se	rial port inte	ial port inter errupt is dis errupt is ena	abled		
5,6	RSV	0	Reserved					
7	EA	0	EA = 0 dis	sable all inte	nterrupts (g errupts t source is i			

2.9.1 8052 Standard Interrupt Enable Register

2.9.2 Additional Interrupt Sources

All nonstandard 8052 interrupts (USB, I²C, etc.) are connected as an OR to generate an internal INT0. It must be noted that the external INT0 and INT1 are not used. Furthermore, INT0 must be programmed as an active low level interrupt (not edge triggered). A vector interrupt register is provided to identify all interrupt sources (see vector interrupt register definition). Up to 64 interrupt vectors are provided. It is the responsibility of the MCU to read the vector and dispatch the proper interrupt routine.

2.9.3 VECINT: Vector Interrupt Register

7–4

This register contains a vector value identifying the internal interrupt source that trapped to location 0003H. Writing any value to this register removes the vector and update the next vector value (if another interrupt is pending). Note that the vector value is offset. Therefore, its value is in increments of two (bit-0 is set to 0). When no interrupt is pending, the vector is set to 00h. (see Table 2–8: Vector Interrupt Values). As shown, the interrupt vector is divided into two fields; I[2:0] and G[3:0]. The I-field defines the interrupt source within a group (on first come first served basis) and the G-field, which defines the group number. Group G0 is the lowest and G15 is the highest priority.

	7	6	5	4	3	2	1	0	
	G3	G2	G1	G0	12	11	10	0	
-	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/O	
	BIT	NAME	RESET					FUNCTIO	N
	3–1	I[2:0]	000	This field d	efines the ir	nterrupt sou	rce in a giv	en group. Se	ee Table 2–8: Vector Interrupt Values.

010 01	0000	
G[3:0]	0000	This field defines the interrupt group. I[2:0] and G[3:0] combine to produce the actual interrupt vector.
0[0:0]	0000	

G[3:0] (Hex)	l[2:0] (Hex)	VECTOR (Hex)	INTERRUPT SOURCE
0	0	00	No interrupt
1	0	10	NOT USED
1	1	12	Output endpoint-1
1	2	14	Output endpoint-2
1	3	16	Output endpoint-3
1	4–7	18–1E	NOT USED
2	0	20	NOT USED
2	1	22	Input endpoint-1
2	2	24	Input endpoint-2
2	3	26	Input endpoint-3
2	4–7	28–2E	NOT USED
3	0	30	STPOW packet received
3	1	32	SETUP packet received
3	2	34	PWON interrupt
3	3	36	PWOFF interrupt
3	4	38	RESR interrupt
3	5	ЗA	SUSR interrupt
3	6	3C	RSTR interrupt
3	7	ЗE	RESERVED
4	0	40	I2C TXE interrupt
4	1	42	I2C RXF interrupt
4	2	44	Input endpoint-0
4	3	46	Output endpoint-0
4	4–7	48 ightarrow 4E	NOT USED
5–15	Х	$90 \rightarrow FE$	NOT USED

Table 2–8. Vector Interrupt Values

2.9.4 Logical Interrupt Connection Diagram (INT0)

Figure 2–5 represents the logical connection of the interrupt sources and its relation with XINTO#. The priority encoder generates an 8-bit vector, corresponding to 64 interrupt sources (not all are used). The interrupt priorities are hard wired. Vector 4E is the highest and 00 is the lowest.

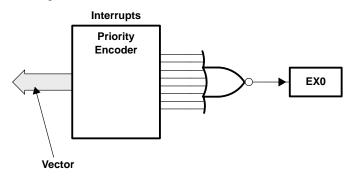


Figure 2–5. Internal Vector Interrupt (EX0)

2.9.5 P2[7:0] Interrupt (INT1)

Figure 2–6 illustrates the conceptual Port-2 interrupt. All Port-2 input signals are connected in a logical OR to generate INT1 interrupt. Note that the inputs are active low and INT1 is programed as an edge-triggered interrupt. In addition, INT1 is connected to the suspend/resume logic for remote wake-up support. As illustrated, XINT-bit in MCU configuration register (MCNFG) is used to select the EXI interrupt source. When XINT = 0, P3.3 is the source, and when XINT = 1, P2[7:0] is the source.

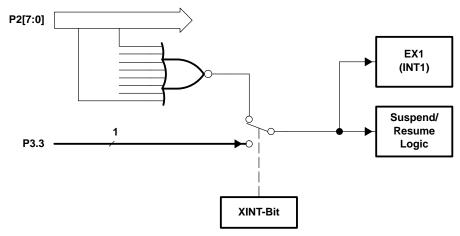


Figure 2–6. P2[7:0] Input Port Interrupt Generation

2.10 I2C Registers

2.10.1 I2CSTA: I2C Status and Control Register

This register is used to control the stop condition for read and write operation. In addition, it provides transmitter and receiver handshake signals with their respective interrupt enable bits.

7	6	5	4	3	2	1	0	
RXF	RIE	ERR	1/4	TXE	TIE	SRD	SWR	
R/C	R/W	R/C	R/W	R/C	R/W	R/W	R/W	
BIT	NAME	RESET					FUNCTIO	N
0	SWR	0			his bit define to an exterr		controller ge	nerates a stop condition when data from I2CDAO
			SWR = 0	Stop condi device.	ition is not g	enerated w	hen data fro	om I2CDAO register is shifted out to an external
			SWR = 1	Stop condi	tion is gener	ated when o	data from I20	CDAO register is shifted out to an external device.
1	SRD	0		condition. Th into I2CDA		s if the I2C o	controller wil	l generate a stop condition when data is received
			SRD = 0	Stop condi	tion is not g	enerated w	hen data fro	m SDA line is shifted into I2CDAI register.
			SRD = 1	Stop condi	tion is gene	rated when	data from S	DA line is shifted into I2CDAI register.
2	TIE	0	TIE = 0 In	hitter empty terrupt disal terrupt enat		able.		
3	TXE	1	I ² C transmit can gene	itter empty. erate an inte	This bit indic errupt.	ates that da	ita can be wr	itten to the transmitter. It can be used for polling or
			TXE = 0	Transmitte	r is full. This	s bit is clear	ed when MC	CU writes a byte to I2CDAO register.
			TXE = 1		r is empty. he SDA shif		ntroller sets	this bit when the content of I2CDAO register is
4	1/4	0		selection. 00 kHz bus 00 kHz bus				
5	ERR	0	MCU. ERR = 0	No bus erro	or			the device does not respond. It is cleared by the when MCU writes a 1. Writing a 0 has no effect.
6	RIE	0	RIE = 0 In	er ready inte terrupt disa terrupt enal		е.		
7	RXF	0		er full. This n interrupt.	bit indicates	that the re	ceiver conta	ins new data. It can be used for polling or it can
			RXF = 0	Receiver is	s empty. Thi	s bit is clea	red when M	CU reads the I2CDAI register.
			RXF = 1		ontains new ed into I2CD		it is set by th	e I2C controller when the received serial data has

2.10.2 I2CADR: I2C Address Register

7	6	5	4	3	2	1	0
A ₆	A5	A ₄	A ₃	A ₂	A ₁	A ₀	R/W
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
BIT	NAME	RESET					FUNCTIO
0	R/W	0	R/W = 0	e command Nrite operat Read operat	ion		
7–1	A[6:0]	0000000	Seven add	dress bits fo	r device ad	dressing.	

This register holds the device address and the read/write command bit.

2.10.3 I2CDAI: I2C Data-Input Register

This register holds the received data from an external device.

7	6	5	4	3	2	1	0	
D ₇	D ₆	D5	D ₄	D3	D ₂	D ₁	D ₀	
R/O	R/O	R/O	R/O	R/O	R/O	R/O	R/O	
BIT	NAME	RESET					FUNCTIO	N
7–0	D[7:0]	0	8-bit input	data from a	n I2C devic	е		

2.10.4 I2CDAO: I2C Data-Output Register

This register holds the data to be transmitted to an external device. Writing to this register starts the transfer on the SDA line.

7	6	5	4	3	2	1	0	
D7	D6	D5	D4	D3	D2	D1	D0	
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
BIT	NAME	RESET					FUNCTIO	N
7–0	D[7:0]	0	8-bit outpu	it data to an	I2C device			

2.11 Read/Write Operations

2.11.1 Read Operation (Serial EEPROM)

A serial read requires a *dummy* byte write sequence to load in the 16-bit data word address. Once the device address word and data word address is clocked out and acknowledged by the device, the MCU starts a current address sequence. The following describes the sequence of events to accomplish this transaction:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SRD] = 0. This forces the I2C controller not to generate a stop condition after the content of I2CDAI register is received.
- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to NOT generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the High-Byte of the EEPROM address into I2CDAO register, starting the transfer on SDA line
- TXE bit in I2CSTA is cleared, indicating busy

- The content of I2CADR register is transmitted to the EEPROM (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the EEPROM (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- No stop condition is generated

EEPROM [Low-byte]

- MCU writes the Low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- This completes the *dummy* write operation. At this point, the EEPROM address is set and the MCU can do a single or a sequential read operation.

2.11.2 Current Address Read Operation

Once the EEPROM address is set the MCU can read a single byte by executing the following steps:

- 1. MCU sets I2CSTA[SRD] = 1, forcing the I2C controller to generate a stop condition after I2CDAI register is received.
- 2. MCU writes the device address (R/W bit = 1) to I2CADR register (read operation).
- 3. MCU writes a dummy byte to I2CDAO register, starting the transfer on SDA line
- 4. RXF bit in I2CSTA is cleared
- 5. The content of I2CADR register is transmitted to the device, preceded by start condition on SDA
- 6. Data from the EEPROM is latched in I2CDAI register (stop condition is transmitted)
- 7. RXF bit in I2CSTA is set, and interrupt the MCU, indicating that the data is available.
- 8. MCU reads I2CDAI register. This clears RXF bit (I2CSTA[RXF] = 0)
- 9. END

2.11.3 Sequential Read Operation

Once the EEPROM address is set, the MCU can execute a sequential read operation by executing the following steps (Note: this example illustrates 32-byte sequential read):

- 1. Device Address
 - MCU sets I2CSTA[SRD] = 0. This forces the I2C controller to not generate a stop condition after I2CDAI register is received
 - MCU writes the device address (R/W bit = 1) to I2CADR register (read operation)
 - MCU writes a dummy byte to I2CDAO register, starting the transfer on SDA line
 - RXF bit in I2CSTA is cleared
 - The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- 2. N-Byte Read (31-bytes)
 - Data from the device is latched in I2CDAI register (stop condition is not transmitted)
 - RXF bit in I2CSTA is set, and interrupt the MCU, indicating that data is available

- MCU reads I2CDAI register, clearing RXF bit (I2CSTA[RXF] = 0)
- This operation repeats 31 times
- 3. Last-Byte read (byte No. 32)
 - MCU sets I2CSTA[SRD] = 1. This forces the I2C controller to generate a stop condition after I2CDAI
 register is received
 - Data from the device is latched in I2CDAI register (Stop condition is transmitted)
 - RXF bit in I2CSTA is set, and interrupt the MCU, indicating that data is available
 - MCU reads I2CDAI register, clearing RXF bit (I2CSTA[RXF] = 0)
 - END

2.11.4 Write Operation (Serial EEPROM)

Byte write operation involves three phases: 1) device address + EEPROM [High–byte] phase, 2) EEPROM [Low–byte] phase, and 3) EEPROM [DATA]. The following describes the sequence of events to accomplish the byte write transaction:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to not generate a stop condition after the content
 of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the high-byte of the EEPROM address into I2CDAO register, starting the transfer on SDA line
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the device (EEPROM high-address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted

EEPROM [Low-byte]

- MCU writes the low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted

EEPROM [DATA]

- MCU sets I2CSTA[SWR] = 1. This forces the I2C controller to generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the DATA to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been transmitted
- I2C controller generates a stop condition after the content of I2CDAO register is transmitted
- END

2.11.5 Page Write Operation

Page write operation is initiated the same way as byte write, with the exception that stop condition is not generated after the first EEPROM [DATA] is transmitted. The following describes the sequence of writing 32-bytes in page mode:

Device Address + EEPROM [High-byte]

- MCU sets I2CSTA[SWR] = 0. This forces the I2C controller to not generate a stop condition after the content of I2CDAO register is transmitted.
- MCU writes the device address (R/W bit = 0) to I2CADR register (write operation)
- MCU writes the high-byte of the EEPROM address into I2CDAO register.
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CADR register is transmitted to the device (preceded by start condition on SDA)
- The content of I2CDAO register is transmitted to the device (EEPROM address)
- TXE bit in I2CSTA is set, and interrupt the MCU, indicating that I2CDAO register has been sent.

EEPROM [Low-byte]

- MCU writes the low-byte of the EEPROM address into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device. (EEPROM address)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent.

31 Bytes EEPROM [DATA]

- MCU writes the DATA to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the device (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent.
- This operation repeats 31 times.

Last Byte EEPROM [DATA]

- MCU sets I2CSTA[SWR] = 1. This forces the I2C controller to generate a stop condition after the content
 of I2CDAO register is transmitted.
- MCU writes the last DATA byte to be written to the EEPROM into I2CDAO register
- TXE bit in I2CSTA is cleared, indicating busy
- The content of I2CDAO register is transmitted to the EEPROM (EEPROM data)
- TXE bit in I2CSTA is set, and interrupts the MCU, indicating that I2CDAO register has been sent
- I2C controller generates a stop condition after the content of I2CDAO register is transmitted
- END of 32-byte page write operation

3 Electrical Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature (unless otherwise noted)[†]

Supply voltage, V _{CC}	–0.5 V to 4 V
Input voltage, V ₁	–0.5 V to V _{CC} + 0.5 V
Output voltage, V _O	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK}	±20 mA
Output clamp current, I _{OK}	
Storage temperature	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

3.2 Commercial Operating Condition

	PARAMETER	MIN	NOM	MAX	UNIT
VCC	Supply voltage	3	3.3	3.6	V
VI	Input voltage	0		VCC	V
VIH	High level input voltage	2		VCC	V
VIL	Low level input voltage	0		0.8	V
T _A	Operating temperature	0		70	°C

3.3 Electrical Characteristics, $T_A = 25^{\circ}C$, $V_{CC} = 3.3 V \pm 0.3V$, GND = 0 V

	PARAMETER	TEST CONDITIONS	MIN	NOM	MAX	UNIT
VOH	High-level output voltage	I _{OH} = -4 mA	V _{CC} -0.5			V
VOL	Low-level output voltage	$I_{OL} = 4 \text{ mA}$			0.5	V
V_{IT+}	Positive input threshold voltage	$V_{I} = V_{IH}$			2	V
V_{IT-}	Negative input threshold voltage	$V_{I} = V_{IH}$	0.8			V
V _{hys}	Hysteresis (V _{IT+} – V _{IT} –)	$V_{I} = V_{IH}$		1		V
IIН	High-level input current	$V_{I} = V_{IH}$			±1	μΑ
١ _{IL}	Low-level input current	$V_{I} = V_{IL}$			±1	μΑ
IOZ	Output Leakage Current (Hi-Z)	$V_I = V_{CC} \text{ or } V_{SS}$			10	μΑ
Cl	Input capacitance			5		pF
CO	Output capacitance			7		pF
ICC	Quiescent			25	45	mA
ICCx	Suspend			45		μΑ

4 Application

4.1 Examples

Figure 4–1 illustrates the Port-3 pins that are assigned to drive the four example LEDs. For the connection example shown, P3[7:4] can sink up to 12 mA (open-drain output). Figure 4–2 illustrates the partial connection bus power mode. Figure 4–3 shows the USB upstream connection, and Figure 4–4 illustrates the downstream connection (only one port shown).

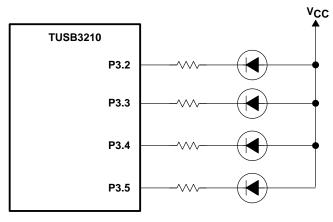


Figure 4–1. Example LED Connection

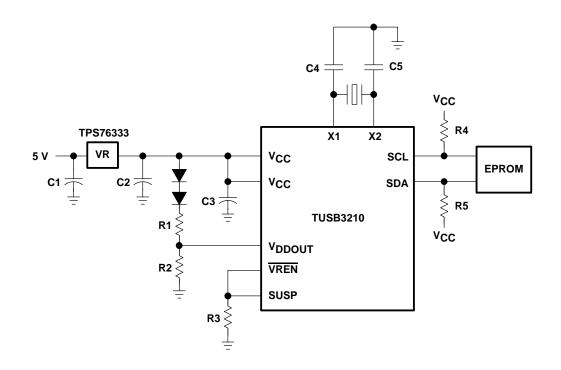


Figure 4–2. Partial Connection Bus Power Mode

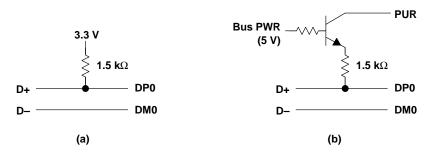
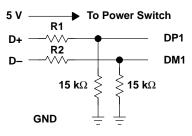


Figure 4–3. Upstream Connection (a) Non-Switching Power Mode (b) Switching Power Mode



NOTE: Ferrite beads can be used on power lines to help ESD.

Figure 4–4. Downstream Connection – (Only One Port Shown)

4.2 Reset Timing

There are two requirements for the reset signal timing. First, the reset window should be between 100 μ sec and 10 msec. At power up, this time is measured from the time the power ramps up to 90% of the nominal Vcc until the reset signal goes high (above 1.2 V). The second requirement is that the clock has to be valid during the last 60 μ sec of the reset window. These two requirements are depicted in Figure 4–5. Notice that when using a 12 MHz crystal or the 48 MHz oscillator, the clock signal may take several milliseconds to ramp up and become valid after power up. Therefore, the reset window may need to be elongated up to 10 msec. to ensure that there is a 60 μ sec overlap with a valid clock.

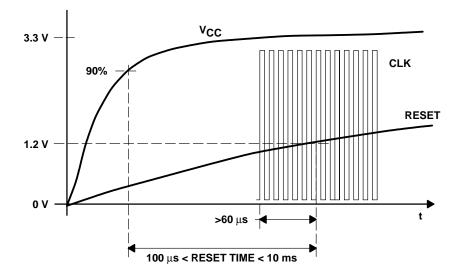
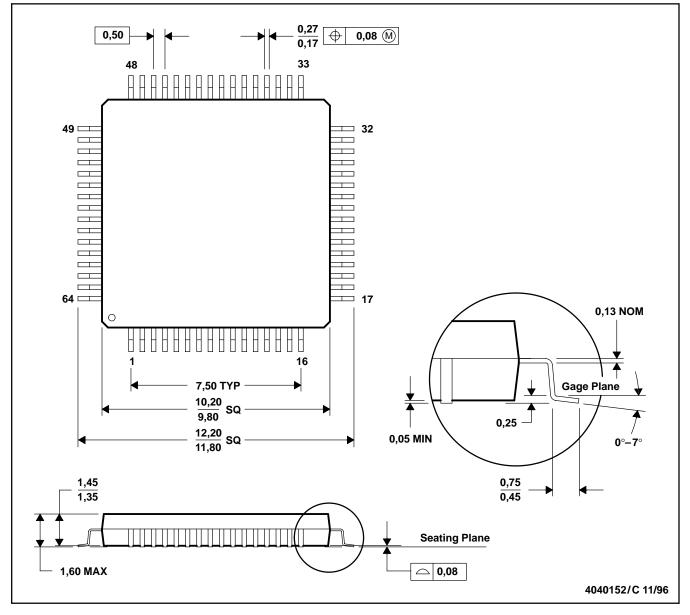


Figure 4–5. Reset Timing

5 Mechanical Data

PM (S-PQFP-G64)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026
- D. May also be thermally enhanced plastic with leads connected to the die pads.